

Title of Change:	Update to FPCN20626XCD to correction on Description and Purpose
Proposed first ship date:	16 September 2015
Contact information:	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume@onsemi.com>.
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>
Change category:	□ Wafer Fab Change
Change Sub-Category(s): Manufacturing Site Change/ Manufacturing Process Chan	
Sites Affected: All site(s) not applicable ON Semiconductor site(s) : External Foundry/Subcon site(s) ON Shenzhen, China	
Description and Purpose:	
FPCN20626XCD announced the change in wire material from gold to copper and change of part number. Affected products will be identified with new part number (changing suffix to "-W"). PART_ID New Part_ID CPH3455-TL-H CPH3455-TL-W MCH6444-TL-H MCH6444-TL-W	
This UN is issued to correct Statement #2 of the Description and purpose of the initially distributed FPCN: <u>From:</u> 2) Changing part number change of XXXXXXX-TL-H from XXXXXX-TL-E	
To: 2) Changing part number change of XXXXXXX-TL-H to XXXXXXX-TL-W	
List of Affected Standard Parts: CPH3455-TL-H MCH6444-TL-H	